



HSEC8-125-01-L-DV-A

HSEC8-149-01-L-DV-A

HSEC8-DV SERIES

(0.80 mm) .0315"

VERTICAL EDGE RATE® CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com/HSEC8-DV

Insulator Material:

Black Liquid Crystal Polymer

Contact:

BeCu

Plating: Au or Sn over

50µ" (1.27 µm) Ni

Current Rating: 2.8 A per pin

(2 adjacent pins powered)

Operating Temp:

-55°C to +125°C

Card Insertion Depth:

(3.15 mm) .125" nominal

RoHS Compliant: Yes

Processing:

Lead-Free Solderable: Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (10-60)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. 600271_0_000

OTHER SOLUTIONS

- Standard high speed interface cards for 19 mm, 25 mm & 30 mm mated heights, single-ended & differential applications. See HSC8 Series.

ALSO AVAILABLE (MOQ Required)

- Guide rails
- Pass-through options
- Other platings
- Custom cards for low-cost stack height customization
- Samtec supplied card layout/artwork to make your own cards
- Specialty card shapes
- Contact Samtec.

CABLE	CONNECTOR
ECDP-04	HSEC8-109-L2
ECDP-08	HSEC8-113-L2
ECDP-16	HSEC8-125-L2
ECDP-32	HSEC8-149-L2

Notes:

While optimized for 50Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75Ω applications. Contact Samtec for further information.

Some lengths, styles and options are non-standard, non-returnable.

Mates with:
(1.60 mm) .062" card,
(2.36 mm) .093" card,
ECDP, HSC8



Mates with (1.60 mm) .062"
or (2.36 mm) .093" cards

HIGH SPEED CABLE APPLICATIONS

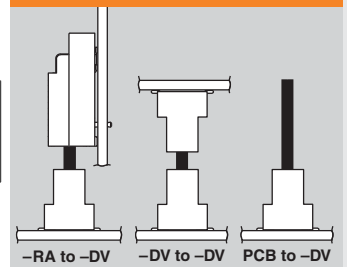


HSEC8 7.98 mm Stack Height	Rated @ 3dB Insertion Loss	
	with PCB effects*	w/o PCB effects**
Single-Ended Signaling	8 GHz / 16 Gbps	17 GHz / 34 Gbps
Differential Pair Signaling	10.5 GHz / 21 Gbps	15.5 GHz / 31 Gbps

*Performance data includes effects of a non-optimized PCB.
**Test board losses de-embedded from performance data.
Complete test data available at www.samtec.com/HSEC8-DV or contact sig@samtec.com

Finalinch 28+
CERTIFIED Gbps

BOARD-TO-BOARD APPLICATIONS



HSEC8	1	POSITIONS PER ROW	CARD THICKNESS	PLATING OPTION	DV	A	OTHER OPTION
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09, 10, 13, 20,
25, 30, 37, 40, 49,
50, 60, 70, 80, 100

(13, 25, 49 only available with -L or -L2 option;
09 only available with -L2 option;
37 only available with -L option)

-01
= (1.60 mm) .062"
thick card
-03
= (2.36 mm) .093"
thick card

-L
= 10µ" (0.25 µm) Gold on contact,
Matte Tin on tail

-S
= 30µ" (0.76 µm) Gold on contact,
Matte Tin on tail

-K
= (7.01 mm) .276" DIA
Polyimide Film
Pick & Place Pad
(with -01 card)
= (6.25 mm) .246" DIA
Polyimide Film
Pick & Place Pad
(with -03 card)

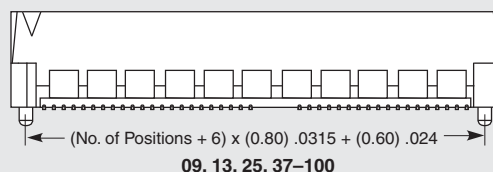
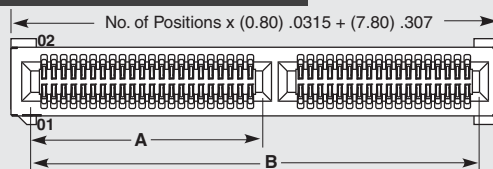
-BL
= Board Locks
(40, 50, 60, 80 only)
(Other sizes available.
Contact Samtec.)
(Weld tab standard)

-L
= Latching Option
(13, 25, 37, 49 only)
(Weld tab standard)

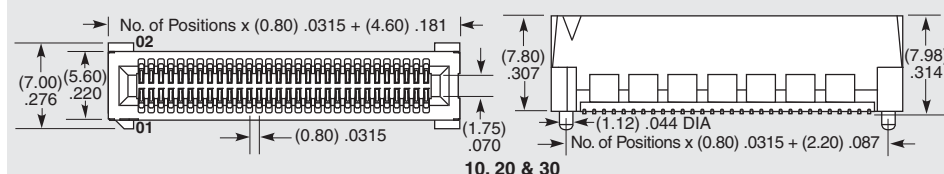
-L2
= ECDP Latching
(09, 13, 25, 49 only)
(For use with ECDP)
(Weld tab standard)

-WT
= Weld tab

-TR
= Tape & Reel
(09 - 70 only)



09, 13, 25, 37-100



10, 20 & 30

WWW.SAMTEC.COM

Due to technical progress, all designs, specifications and components are subject to change without notice.